



IFW/S

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Farnworth et. al.

Serial No.: 10/624,766

Filed: July 22, 2003

For: HERMETIC CHIP AND METHOD OF
MANUFACTURE

Confirmation No.: 6771

Examiner: T. Magee

Group Art Unit: 2811

Attorney Docket No.: 2269-2741.6US
(95-0804.06/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

December 9, 2004
Date


Signature

Deborah L. Hendricks
Name (Type/Print)

AMENDMENT

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This amendment is in response to the Office Action of September 9, 2004, whose initial period of response is set to expire on December 9, 2004.

Amendments to the Title appear on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 5 of this paper.

IN THE TITLE:

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

~~HERMETIC CHIP IN WAFER FORM AND METHOD OF MANUFACTURE~~